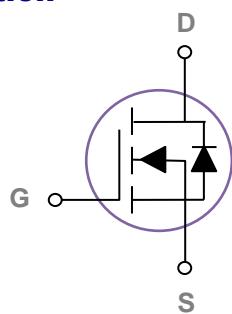
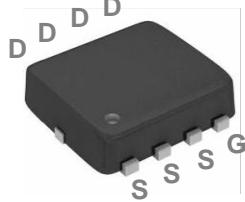


### General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### PPAK3x3 Pin Configuration



BVDSS	RDS(ON)	ID
20V	5.4mΩ	65A

### Features

- 20V,65A,  $RDS(ON) = 5.4m\Omega$  @ $VGS = 4.5V$
- Improved dv/dt capability
- Green Device Available
- Suit for 1.8V Gate Drive Applications

### Applications

- Load Switch
- POL Applications
- SMPS 2<sup>nd</sup> SR
- Li-Battery Protection

### Absolute Maximum Ratings $T_c=25^\circ C$ unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	20	V
$V_{GS}$	Gate-Source Voltage	$\pm 10$	V
$I_D$	Drain Current – Continuous ( $T_c=25^\circ C$ )	65	A
	Drain Current – Continuous ( $T_c=100^\circ C$ )	41	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	260	A
$P_D$	Power Dissipation ( $T_c=25^\circ C$ )	44.6	W
	Power Dissipation – Derate above 25°C	0.36	W/°C
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	°C/W
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	2.8	°C/W

**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	20	---	---	V
△BV <sub>DSS</sub> /△T <sub>J</sub>	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C, I <sub>D</sub> =1mA	---	0.01	---	V/°C
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =20V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	1	uA
		V <sub>DS</sub> =16V, V <sub>GS</sub> =0V, T <sub>J</sub> =125°C	---	---	10	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±10V, V <sub>DS</sub> =0V	---	---	±100	nA

**On Characteristics**

R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =4.5V, I <sub>D</sub> =20A	---	4.5	5.4	mΩ
		V <sub>GS</sub> =2.5V, I <sub>D</sub> =15A	---	5.5	6.8	mΩ
		V <sub>GS</sub> =1.8V, I <sub>D</sub> =10A	---	6.8	8.8	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	0.3	0.6	1	V
			---	2	---	mV/°C
gfs	Forward Transconductance	V <sub>DS</sub> =10V, I <sub>S</sub> =5A	---	20	---	S

**Dynamic and switching Characteristics**

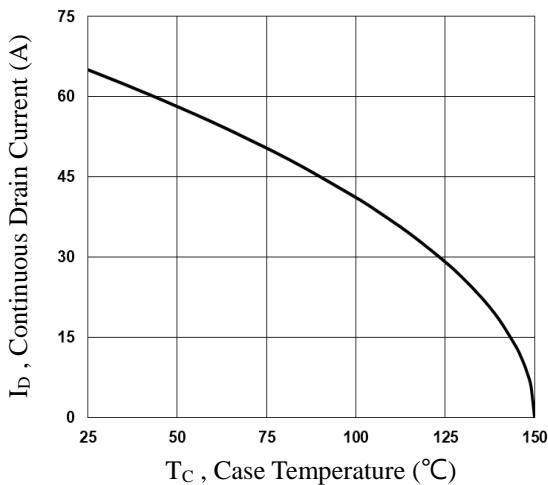
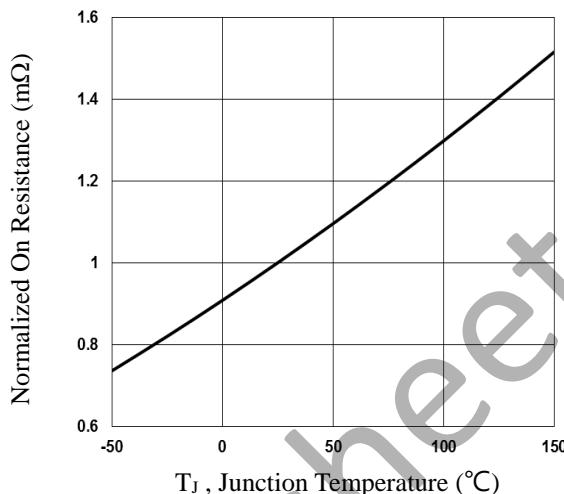
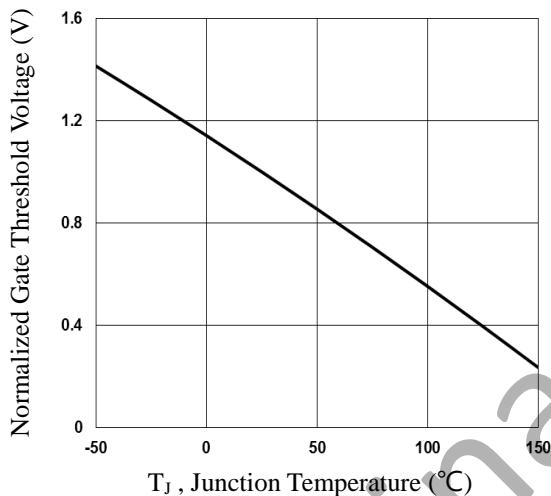
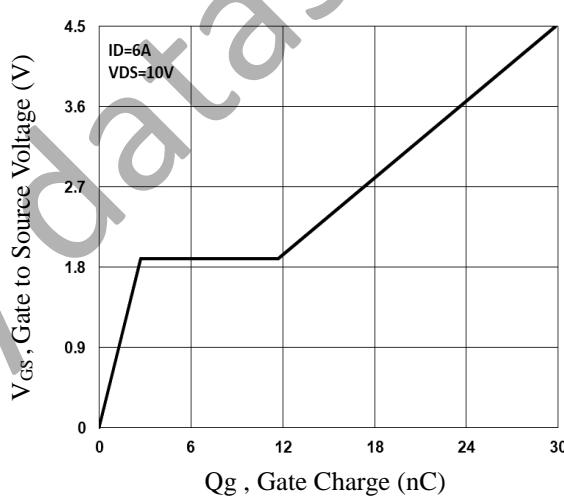
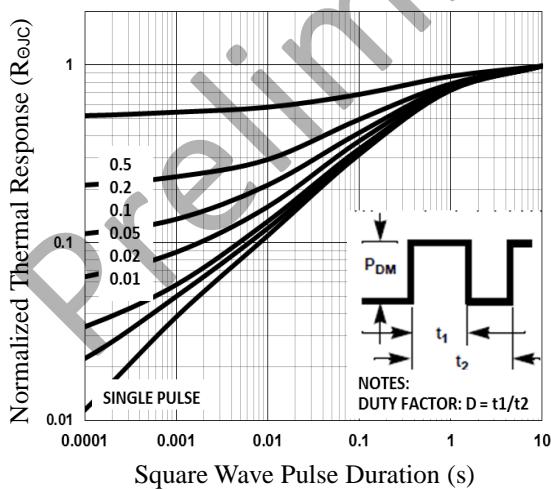
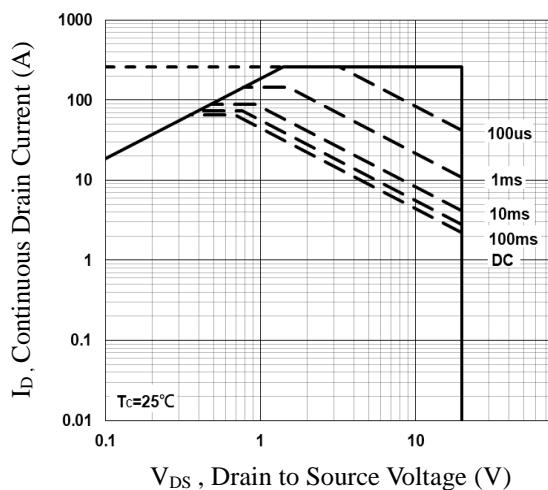
Q <sub>g</sub>	Total Gate Charge <sup>2,3</sup>	V <sub>DS</sub> =10V, V <sub>GS</sub> =4.5V, I <sub>D</sub> =6A	---	29.8	45	nC
Q <sub>gs</sub>	Gate-Source Charge <sup>2,3</sup>		---	2.7	6	
Q <sub>gd</sub>	Gate-Drain Charge <sup>2,3</sup>		---	9	14	
T <sub>d(on)</sub>	Turn-On Delay Time <sup>2,3</sup>	V <sub>DD</sub> =10V, V <sub>GS</sub> =4.5V, R <sub>G</sub> =25Ω I <sub>D</sub> =1A	---	13.5	26	ns
T <sub>r</sub>	Rise Time <sup>2,3</sup>		---	29	55	
T <sub>d(off)</sub>	Turn-Off Delay Time <sup>2,3</sup>		---	66.9	127	
T <sub>f</sub>	Fall Time <sup>2,3</sup>		---	19.2	36	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =10V, V <sub>GS</sub> =0V, F=1MHz	---	1920	2790	pF
C <sub>oss</sub>	Output Capacitance		---	280	410	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	180	270	

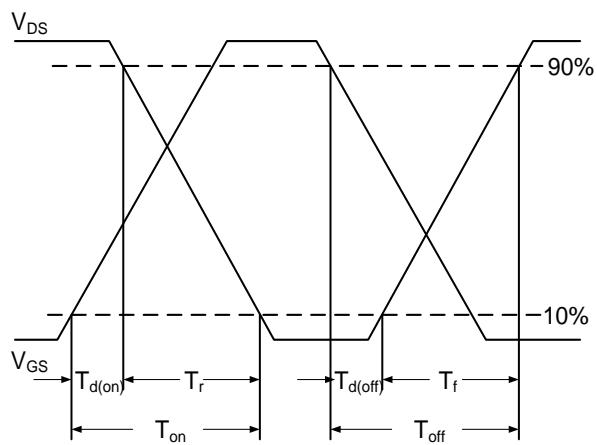
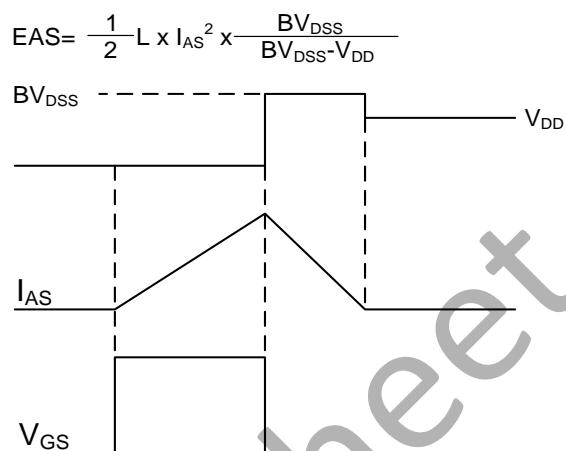
**Drain-Source Diode Characteristics and Maximum Ratings**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>s</sub>	Continuous Source Current	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	65	A
I <sub>SM</sub>	Pulsed Source Current		---	---	130	A
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>s</sub> =1A, T <sub>J</sub> =25°C	---	---	1	V

Note :

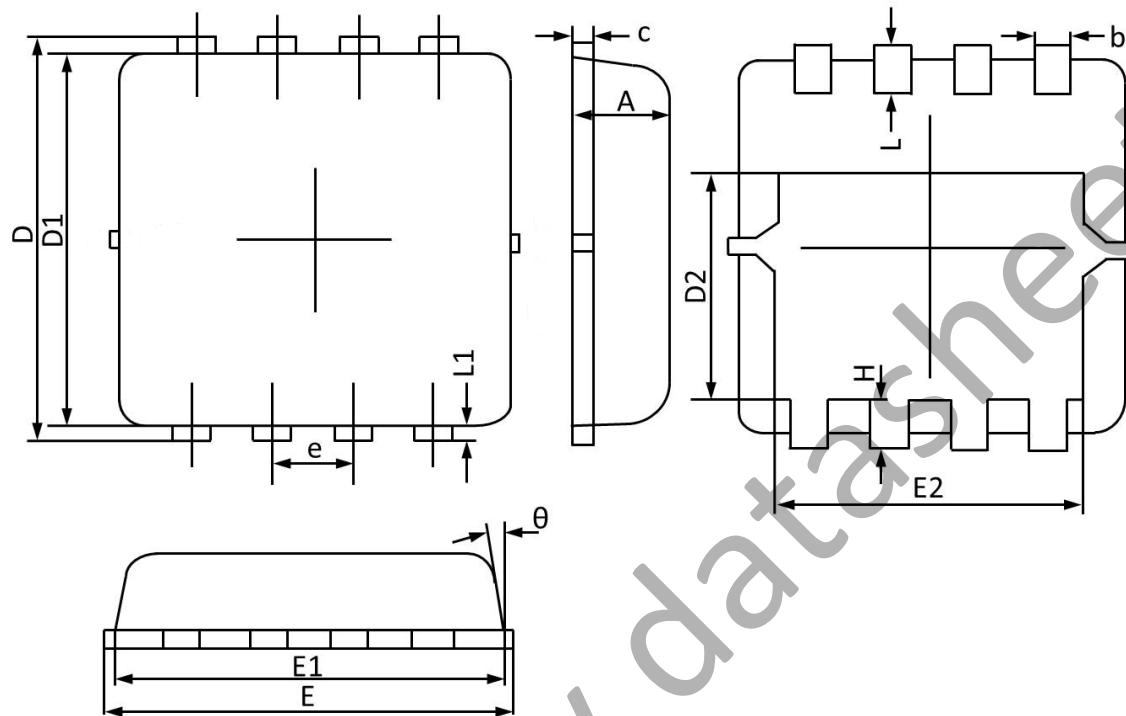
- Repetitive Rating : Pulsed width limited by maximum junction temperature.
- The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.
- Essentially independent of operating temperature.


**Fig.1 Continuous Drain Current vs. TC**

**Fig.2 Normalized RDSON vs. TJ**

**Fig.3 Normalized Vth vs. TJ**

**Fig.4 Gate Charge Waveform**

**Fig.5 Normalized Transient Response**

**Fig.6 Maximum Safe Operation Area**


**Fig.7** Switching Time Waveform

**Fig.8** EAS Waveform

Preliminary datasheet

## PPAK3x3 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	0.900	0.700	0.035	0.028
b	0.350	0.240	0.014	0.009
c	0.250	0.100	0.010	0.004
D	3.450	3.050	0.136	0.120
D1	3.200	2.900	0.126	0.114
D2	1.850	1.350	0.073	0.053
E	3.400	3.000	0.134	0.118
E1	3.250	2.900	0.128	0.114
E2	2.600	2.350	0.102	0.093
e	0.65BSC		0.026BSC	
H	0.500	0.300	0.020	0.012
L	0.500	0.300	0.020	0.012
L1	0.200	0.070	0.008	0.003
θ	12°	0°	12°	0°

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